

LMBR0520ET1G thru LMBR0540ET1G

Schottky Barrier Rectifiers

Reverse Voltage 20 to 40V Forward Current 0.5A

FEATURES

- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- * Low power loss, high efficiency
- * For use in low voltage high frequency inverters, free wheeling, and polarity protection applications
- * Guardring for over voltage protection
- * High temperature soldering guaranteed: 260°C/10 seconds at terminals

Mechanical Data

Case: SOD-323HE

molded plastic over sky die

Terminals: Plated leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position Any

Weight 0.0053 g

Handling precaution None

1. Electrical Characteristic

Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

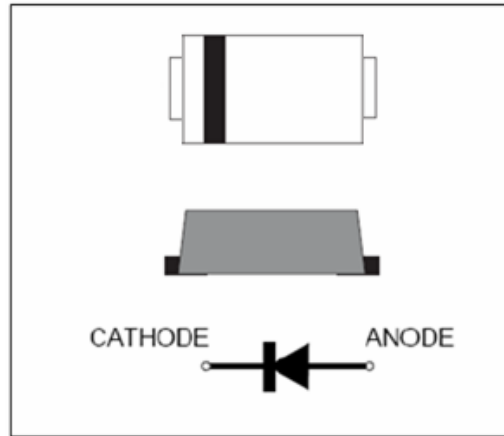
Parameter Symbol	symbol	LMBR0520ET1G	LMBR0530ET1G	LMBR0540ET1G	Unit
device marking code		052	053	054	
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	V
Maximum RMS voltage	V_{RMS}	14	21	28	V
Maximum DC blocking voltage	V_{DC}	20	30	40	V
Maximum average forward rectified current at TC = 75°C	$I_{F(AV)}$	0.5			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	22			A
Typical thermal resistance (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	210 70			°C/W
Operating junction temperature range	T_J	-55 to +125			°C
storage temperature range	T_{STG}	-55 to +150			°C

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR0520ET1G	LMBR0530ET1G	LMBR0540ET1G	Unit
Maximum instantaneous forward voltage at ($I_F = 0.5 A, T_J = 25^\circ C$)	V_F	0.43	0.45	0.55	V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ C$ $T_j = 100^\circ C$	I_R	0.25 8	0.130 10	0.03 10	mA
Typical junction capacitance at 4.0V, 1MHz	C_J	160			PF

NOTES:

1. 8.0mm² (.013mm thick) land areas



We declare that the material of product is Halogen free (green epoxy compound)

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2. Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

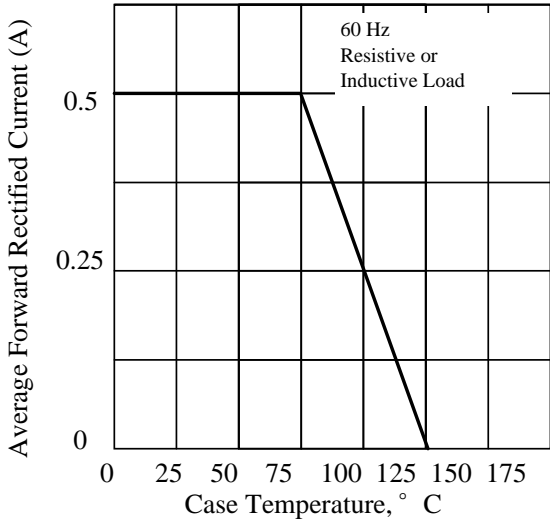


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

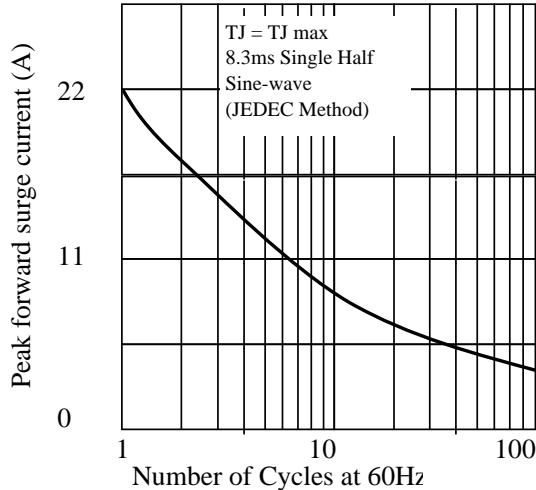


Fig 3. - Typical Instantaneous Forward Characteristics

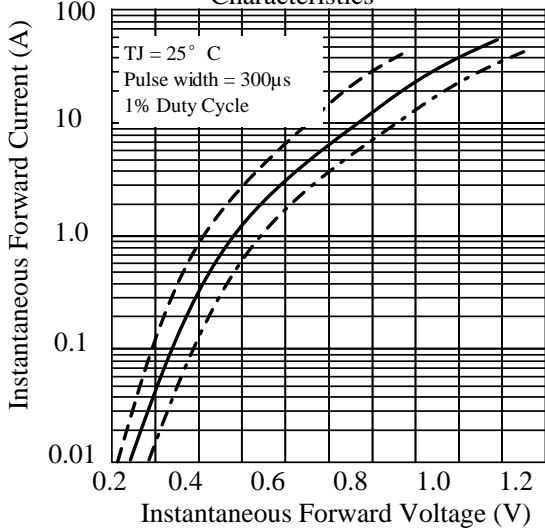


Fig 4. - Typical Reverse Characteristics

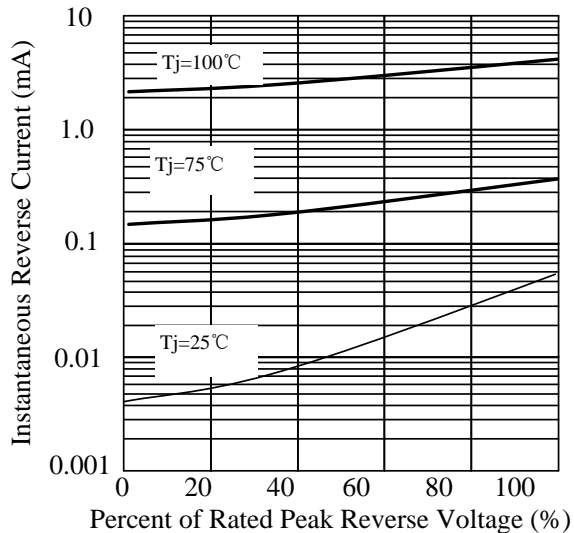


Fig 5. - typical transient thermal impedance

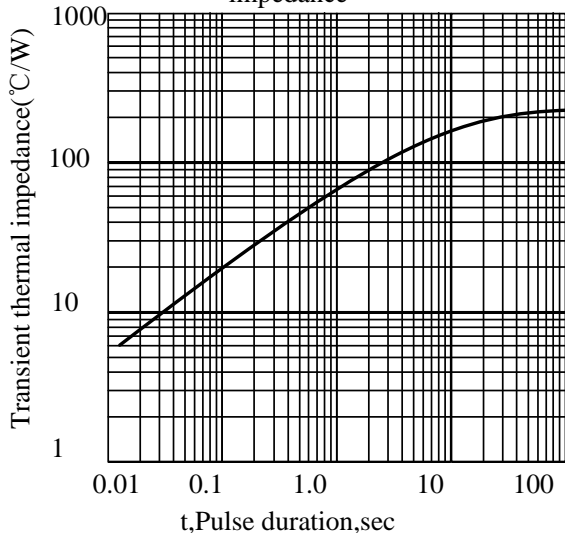
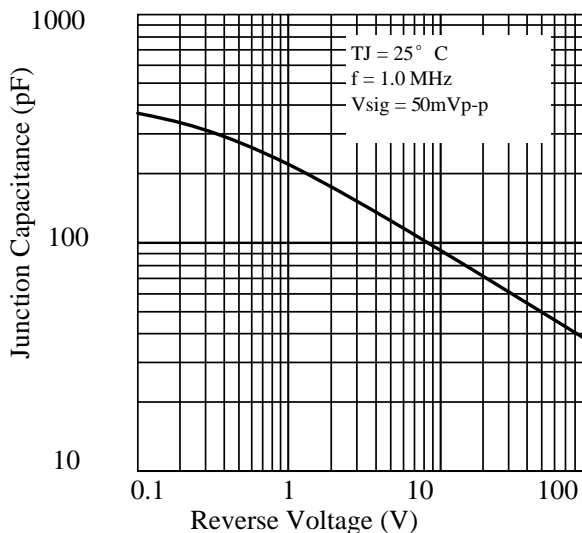
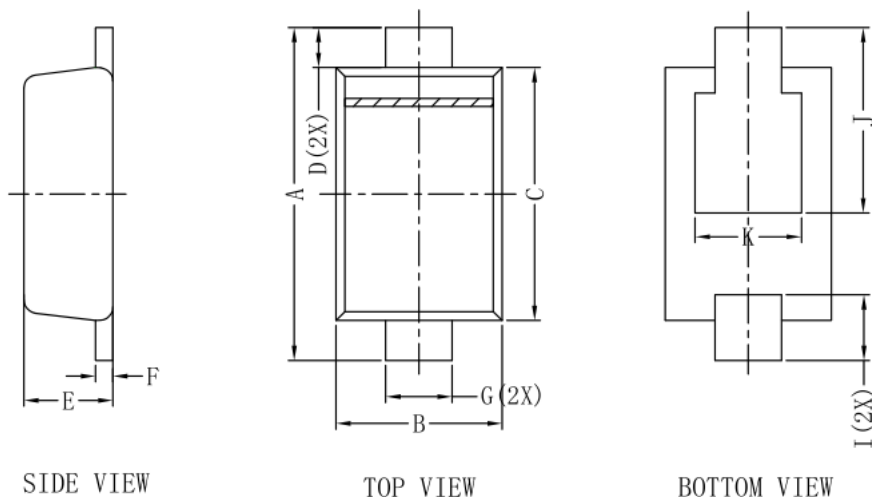


Fig 6. - Typical Junction Capacitance



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3. dimension:



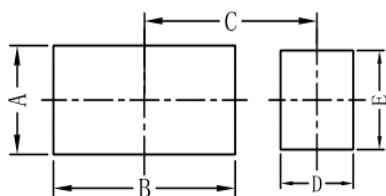
SOD323HE			
DIM	MIN	MAX	Typ.
A	2.30	2.70	2.55
B	1.20	1.35	1.25
C	1.75	1.95	1.90
D	-	-	0.30
E	0.55	0.75	0.67
F	0.10	0.20	0.15
G	0.45	0.65	0.50
I	0.40	0.70	0.50
J	1.15	1.55	1.40
K	-	-	0.80
All Dimensions in mm			

GENERAL NOTES

1. Top package surface finish $Ra0.4 \pm 0.2 \mu m$
2. Bottom package surface finish $Ra0.7 \pm 0.2 \mu m$

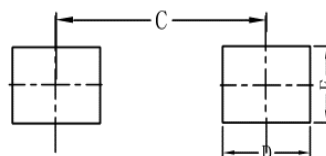
Suggested solder pad layout

RECOMMENDED PAD



SOD323HE	
DIM	(mm)
A	1.1
B	2.0
C	1.9
D	0.8
E	1.0

COMPATIBLE PAD

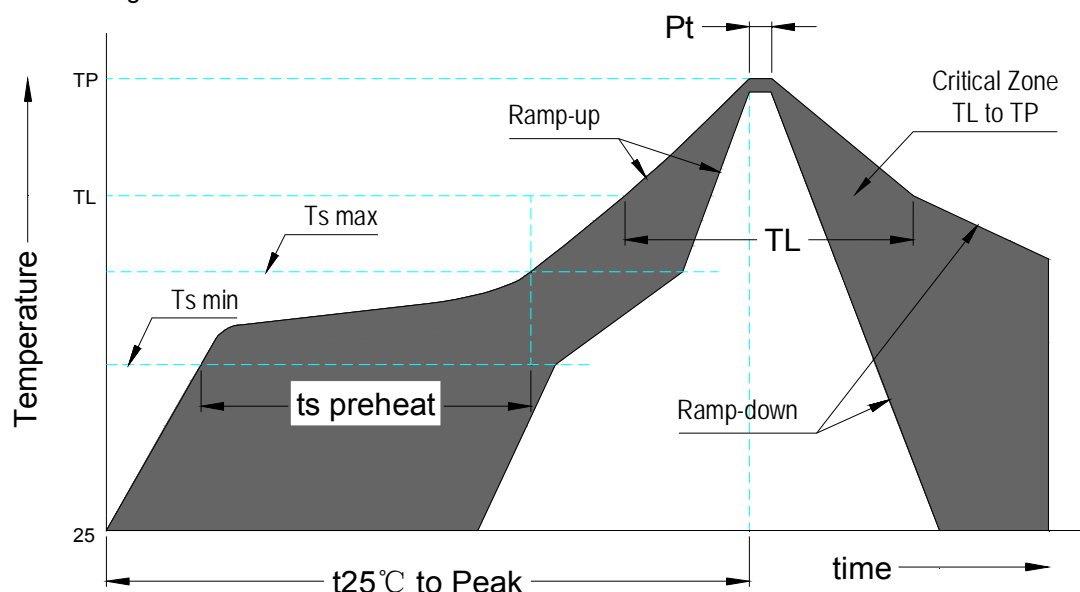


SOD323HE	
DIM	(mm)
D	1.0
E	0.8
C	2.4

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5. Suggested thermal profile for soldering process

1. Storage environment : Temperature=5~40°C Humidity=55±25%
2. Reflow soldering of surface-mount device



3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat	
- Temperature Min(T _{smin})	150°C
- Temperature Max(T _{smax})	200°C
- Time(min to max)(t _s)	60~120sec
T _{smax} to T _L	
- Ramp-up Rate	<3sec
Time maintained above:	
- Temperature (T _L)	217°C
- Time(t _L)	60-260sec
Peak Temperature(T _P)	255 -0/+5°C
Time within 5°C of actual Peak Temperature(T _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

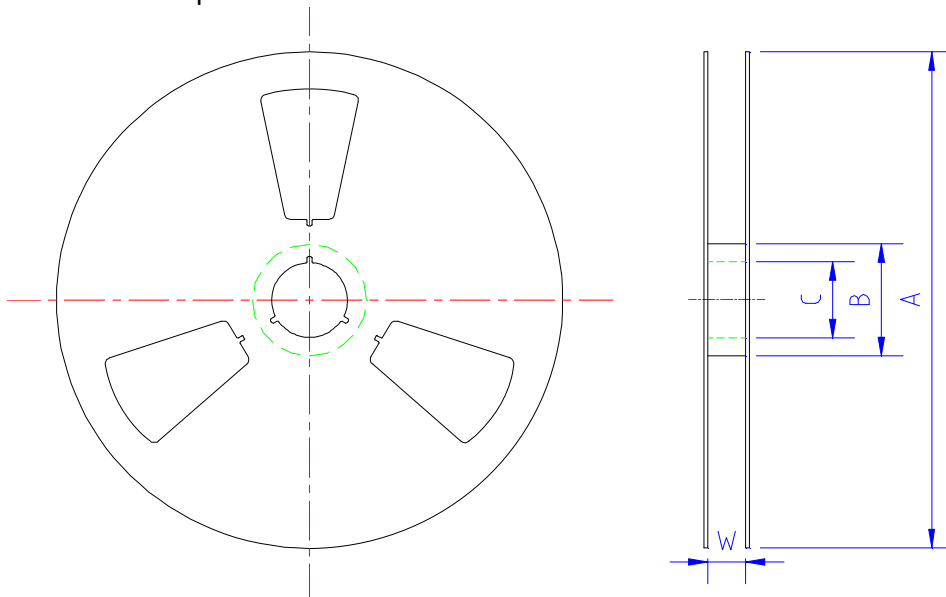
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6.High reliability test capabilities

Item Test	Condition	Reference
Solder Resistance	at 260±5°C for 10±2sec immerse	MIL-STD-750D METHOD-2031
Solderability	at 245±5°C for 5 sec	MIL-STD-202F METHOD-208
High Temperature Reverse Bias	V _R =80% rate at T _j =125°C for 168hrs	MIL-STD-750D METHOD-1038
Forward Operation Life	Rated average rectifier current T _A =25°C for 500hrs	MIL-STD-750D METHOD-1027
Intermittent Operation Life	T _A =25°C , I _F =I _o	MIL-STD-750D METHOD-1036
Pressure Cooker	15P _{SIG} at T _A =121°C for 4hrs	JESD22-A102
Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. Total 10 cycles	MIL-STD-750D METHOD-1051
Thermal Shock	0°C for 5min. Rise to 100°C for 5min. Total 10 cycles	MIL-STD-750D METHOD-1056
Forward Surge	8.3ms single half sine-wave superimposed on rated load,one surge	MIL-STD-750D METHOD-4066-2
Humidity	at T _A =85°C , R _H =85% for 1000hrs	MIL-STD-750D METHOD-1021
High Temperature Storage Life	at 150°C for 1000hrs	MIL-STD-750D METHOD-1031

5.1 、 SMD Packing Reel Spec & Packing Quantity

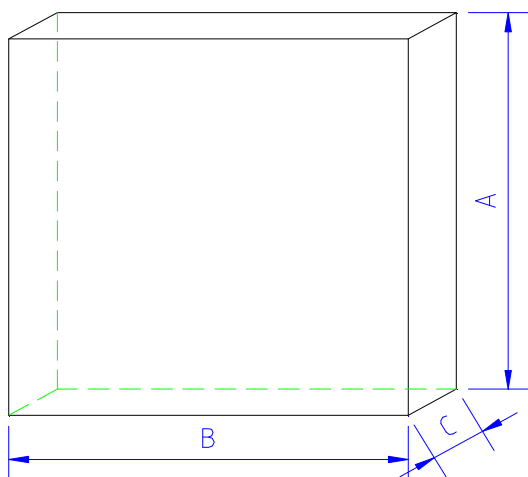
5.1.1 Reel Packing
A. Reel Spec



unit: mm

SPEC	A	B	C	W	Quantity/Reel
SMA-FL 7" reel	177.0±2.0	54.0±0.5	13.0±0.5	13.2±0.2	3K
TO277 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K
SOD123FL 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SOD323HE 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SMB-FL 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K

B. 13" reel packing box



unit: mm

size	A	B	C
	335±5.0	335±2.0	40±1.0

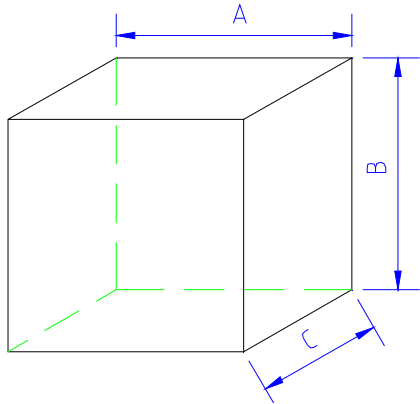
as per above packing

Spec	Q' ty/Box
TO277 13" reel	10K
SMB-FL 13" reel	10K

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Power Diode SMD Package Packing Spec

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C. 7" reel packing box



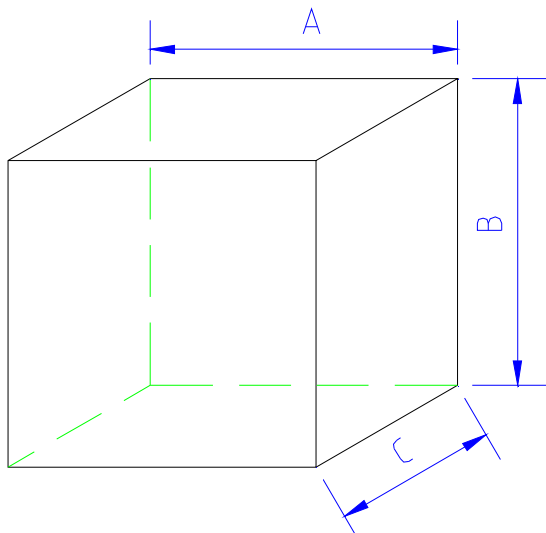
unit: mm

	A	B	C
SMA-FL SOD123FL SOD323HE	186±2.0	139±2.0	185±2.0

as per above packing

	Q' ty/Box
SMA-FL	30K
SOD123FL	30K
SOD323HE	30K

D. reel packing carton



unit: mm

	A	B	C
size	350±2.0	340±2.0	350±2.0

as per above packing

Spec	Q' ty/Carton
TO277 13" reel	80K
SMB-FL 13" reel	80K

unit: mm

	A	B	C
SMA-FL SOD123FL SOD323HE	455±2.0	400±2.0	410±2.0

as per above packing

Spec	Q' ty/Carton
SMA-FL 7" reel	360K
SOD123-FL 7" reel	360K
SOD323HE 7" reel	360K

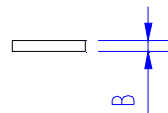
5.1.2 Tape Spec

A. Cover Tape

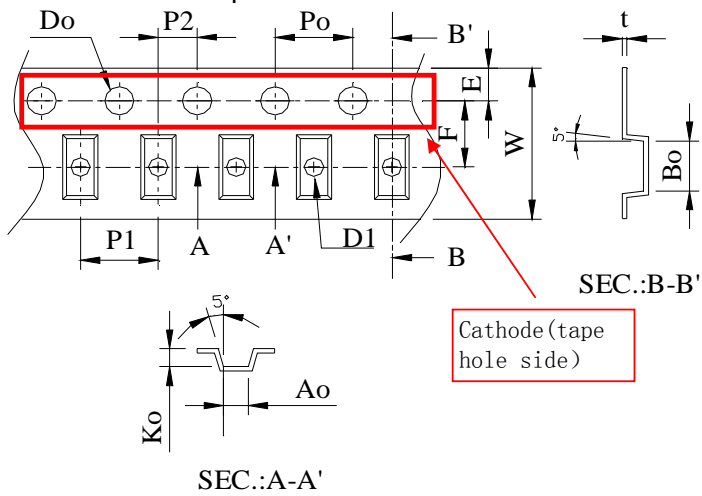


unit: mm

	A	B
SMA-FL SMB-FL TO277	9.5±0.10	0.062±0.007
SOD123FL SOD323HE	5.4±0.10	



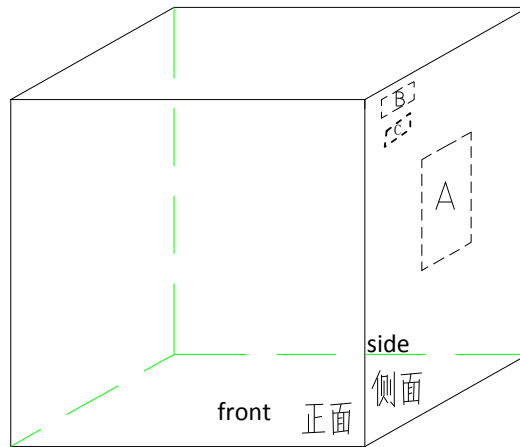
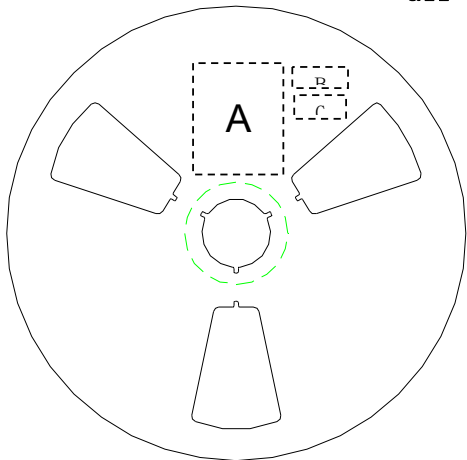
B. Carrier Tape



Item	SOD323HE	SOD123FL	SMA-FL	SMB-FL	TO277
W	8±0.3	8±0.3	12±0.3	12±0.3	12±0.3
P1	4±0.1	4±0.1	4±0.1	8±0.1	8±0.1
E	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
F	3.5±0.05	3.5±0.05	5.5±0.05	5.5±0.05	5.5±0.05
D0	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05
D1	1.1±0.1	1.1±0.1	1.5±0.1	1.55±0.05	1.5±0.1
P0	4±0.1	4±0.1	4±0.1	4±0.1	4±0.1
P2	2±0.05	2±0.05	2±0.05	2±0.05	2±0.05
10P0	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2
A0	1.45±0.1	1.95±0.1	2.83±0.1	3.8±0.1	4.3±0.1
B0	2.75±0.1	3.95±0.1	4.75±0.1	5.75±0.1	6.8±0.1
K0	0.80±0.1	1.30±0.1	1.42±0.1	1.4±0.1	1.35±0.1
T	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05

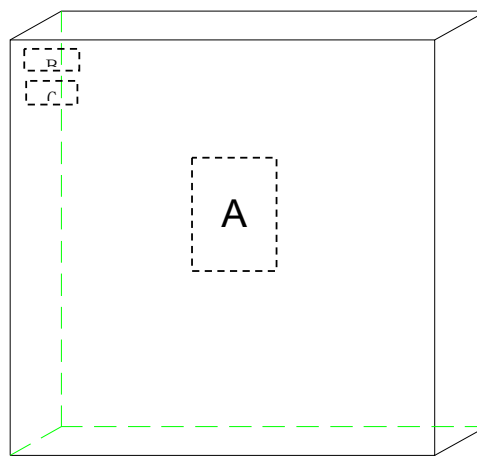
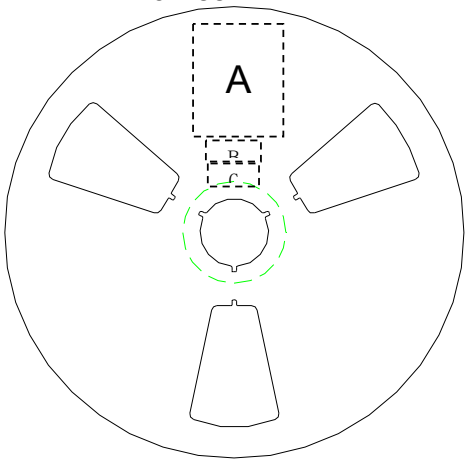
5.2、SMD Power Diode General Packing Spec

A. 7" reel all labels will be at cathode side of reel ;



A:LRC label; B:Environment Label C:Halide free label

B. 13" reel



A:LRC label; B:Environment Labe C:Halide free label

C. Tape lead: face anode side of the reel, upper side is the tape lead position. All labels are at cathode side of the reel.

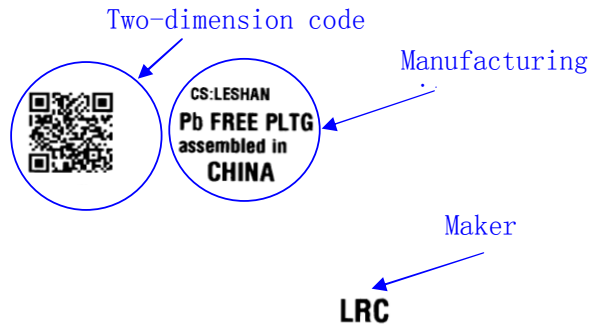


→
User Direction of Feed

标题: Power Diode SMD Package Packing Spec	DOC NO.: WI-258
	Version: 5 Modification: 0
	Page: 6

C. Label Content :
LRC Label

P/N → (1P) LPN: **SM140A**
 Lot No. → (1T) LOT: **140106049X**
 Date code → (9D) DTE: **1403**
 Quantity → (Q) QTY: **10000**



lot: 140106049X: 140106---2014/1/6; 049----lot number:49; X: product code

Environment Label



Halide-free Label



单击下面可查看定价，库存，交付和生命周期等信息

[>>LRC\(乐山无线电\)](#)